

(1.27 mm) .050"

**TFC SERIES** 

**OPTION** 

-RA

= Right-angle

(-01 only)

-A

= Alignment Pin

-LC

= Locking Clip

(Manual Placement

required) (not available

with -RA)

= (6.75 mm) .266"

DIÀ Polyimide film

Pick & Place Pad

-P

= Plastic Pick &

Place Pad

( 5 positions min.)

-TR

= Tape & Reel (-X2 only)

# COST-EFFECTIVE RELIABLE HEADER

#### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?TFC

**Insulator Material:** 

Black Liquid Crystal Polymer Terminal Material: Phosphor Bronze

Plating: Au or Sn over 50 µ" (1.27 µm) Ni Current Pairing: 3.1 A per pin (2 pins powered)

Voltage Rating:
350 VAC mated with SFC **Operating Temp Range:** -55 °C to +125 °C RoHS Compliant:

#### **PROCESSING**

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (03-25) (0.15 mm) .006" max (30-50)\* \*(.004" stencil solution may be available; contact

#### **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality

IPG@samtec.com)



### **ALSO AVAILABLE** (MOQ Required)

· Other sizes

## **Board Mates:**

**Cable Mates:** 

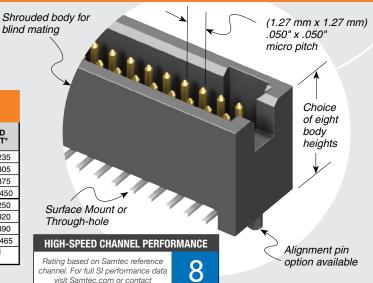
#### **MATED HEIGHTS** LEAD STYLE MATED HEIGHT\* TFC SFC <del>- 01</del> (5.97) .235 - 11 (7.75) .305 \_T1 **– 21** (9.53) .375 (11 43) 450 - 31 - 02 (6.35) .250 - 12 (8.13) .320 - 22 (9.91) .390 - 32 (11.81) .465 \*Processing conditions will

affect mated height

03, 04, 06, 08

(Lead Style -01 & -02 only)

05, 07, 10, 15, 20, 25, 30, 35, 40, 45, 50



NO. PINS **LEAD PLATING** TFC **OPTION** PER ROW STYLE

–X1

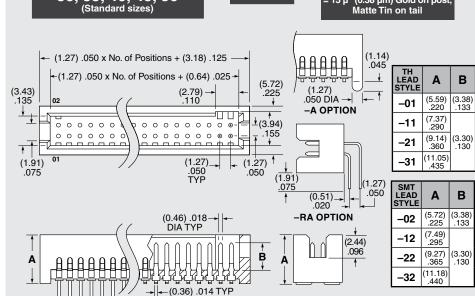
hole **-X2** = Surface Mount

= Through-

SIG@samtec.com

= Gold flash on post, Matte Tin on tail

= 15 μ" (0.38 μm) Gold on post, Matte Tin on tail



Some sizes, styles and options are non-standard,

non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice